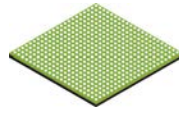


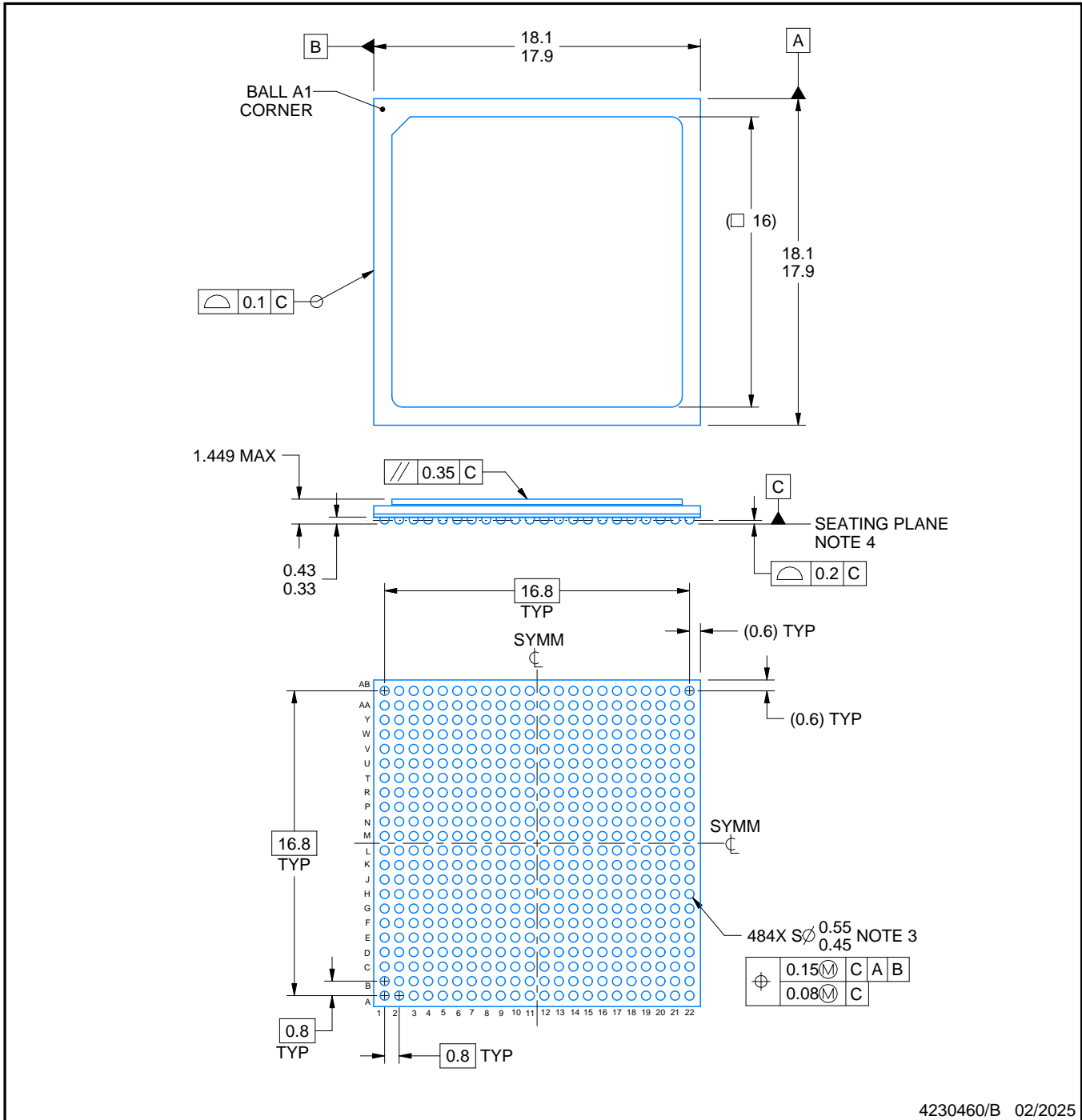
# ANF0484A



# PACKAGE OUTLINE

## FCCSP - 1.449 mm max height

BALL GRID ARRAY



4230460/B 02/2025

### NOTES:

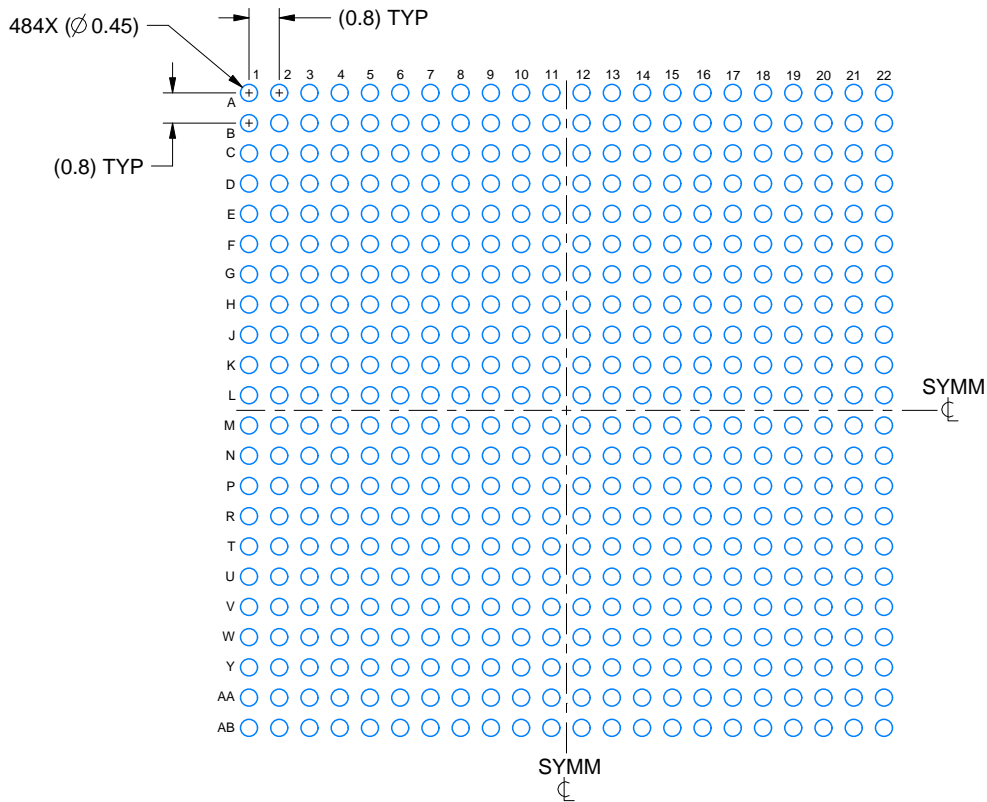
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, post reflow, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.

# EXAMPLE BOARD LAYOUT

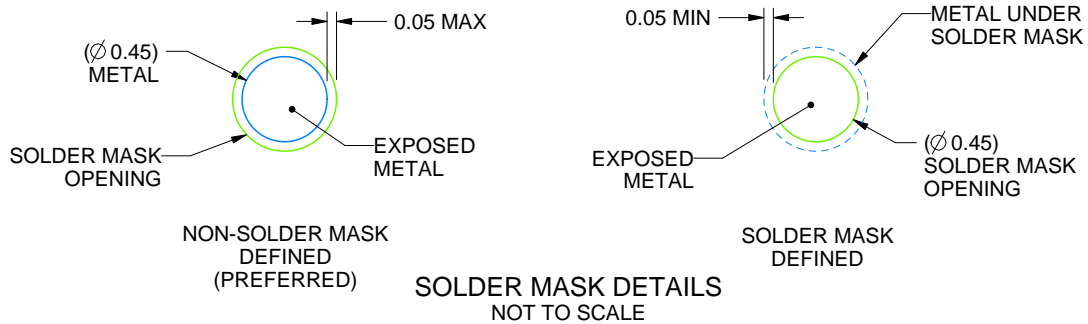
**ANF0484A**

**FCCSP - 1.449 mm max height**

BALL GRID ARRAY



**LAND PATTERN EXAMPLE**  
EXPOSED METAL SHOWN  
SCALE: 5X



4230460/B 02/2025

NOTES: (continued)

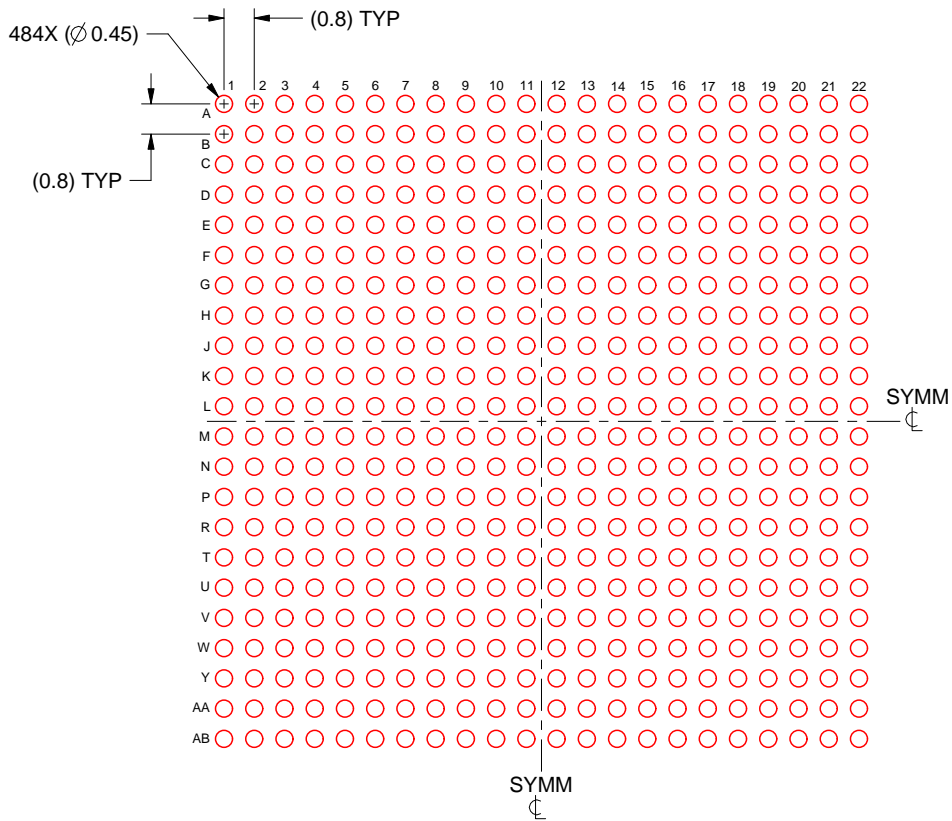
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SPRU811 ([www.ti.com/lit/spru811](http://www.ti.com/lit/spru811)).

# EXAMPLE STENCIL DESIGN

ANF0484A

FCCSP - 1.449 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.15 mm THICK STENCIL  
SCALE: 5X

4230460/B 02/2025

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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